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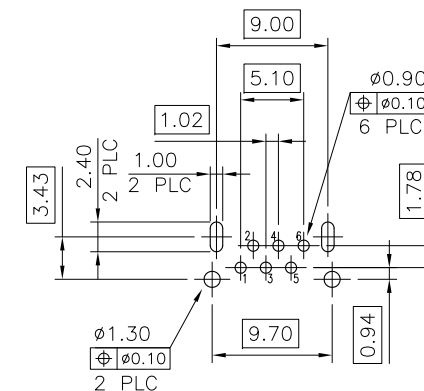
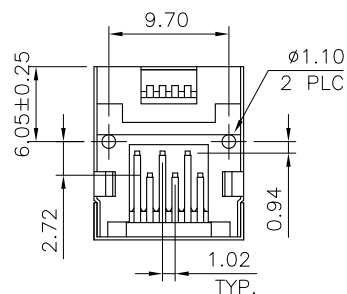
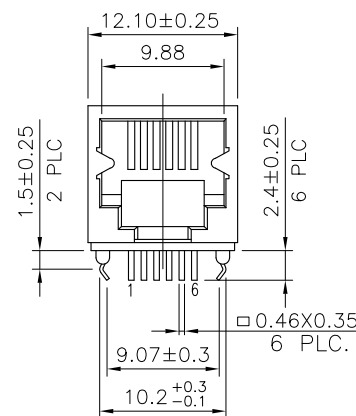
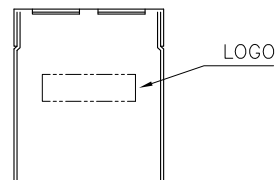
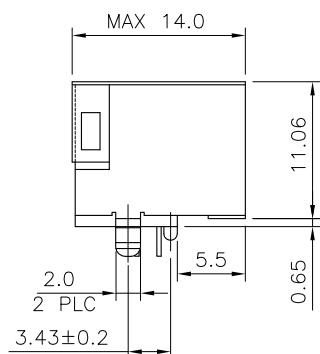
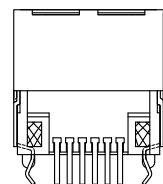
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LOC
DWDIST
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REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
	A2	ECR-12-012115	26OCT12	EL	WK



RECOMMENDED PCB LAYOUT (THICKNESS: 1.6mm)
DIMENSION TOLERANCE: 1 PLC: ±0.1 2PLC: ±0.05

NOTE:

- MATERIAL:
HOUSING: PA46 WITH 30% GF, UL94 V-0, BLACK COLOR.
CONTACTS: PHOSPHOR BRONZE.
SHIELD: BRASS.
- FINISH:
CONTACTS: (SEE TABLE) GOLD PLATED ON CONTACT AREA, GOLD FLASH ON SOLDER TAIL, WITH ENTIRE CONTACT UNDERPLATED 1.27μm [50μ"] MIN. NICKEL.
SHIELD: 0.51μm [20μ"] MIN. NICKEL PLATED.
- WAVE SOLDER CAPABLE TO 265°C PER 109-202, CONDITION B.

4. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

OBSOLETE	6P2C	REEL	1.27μm [50μ"]	2-1734723-8
			0.762μm [30μ"]	2-1734723-7
			0.381μm [15μ"]	2-1734723-6
			0.152μm [6μ"]	2-1734723-5
OBSOLETE	6P2C	TRAY	1.27μm [50μ"]	2-1734723-4
			0.762μm [30μ"]	2-1734723-3
			0.381μm [15μ"]	2-1734723-2
			0.152μm [6μ"]	2-1734723-1
OBSOLETE	6P6C	REEL	1.27μm [50μ"]	-1734723-8
			0.762μm [30μ"]	-1734723-7
			0.381μm [15μ"]	1734723-6
			0.152μm [6μ"]	-1734723-5
OBSOLETE	6P6C	TRAY	1.27μm [50μ"]	-1734723-4
			0.762μm [30μ"]	-1734723-3
			0.381μm [15μ"]	-1734723-2
			0.152μm [6μ"]	1734723-1
	RJ11	PACKAGE	MIN. GOLD THICKNESS	PART NUMBER

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DWN A. WU 10MAR2008

CHK S. HOU 10MAR2008

APVD W. KODAMA 10MAR2008

PRODUCT SPEC
108-57527

APPLICATION SPEC

WEIGHT 3 GRAMS

CUSTOMER DRAWING



TE Connectivity

MODULAR JACK, RJ11,
SINGLE, DIP TYPE

SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
A3	—	©=1734723	—

SCALE — SHEET 1 OF 5 REV A2

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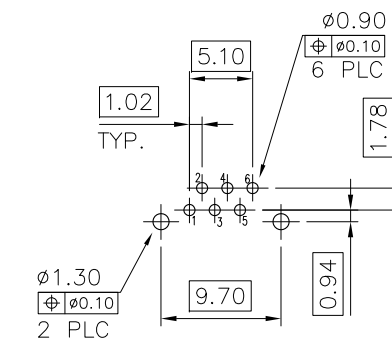
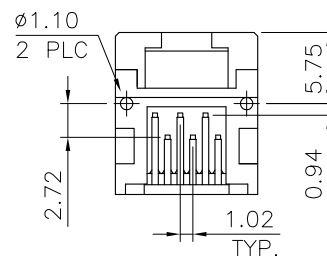
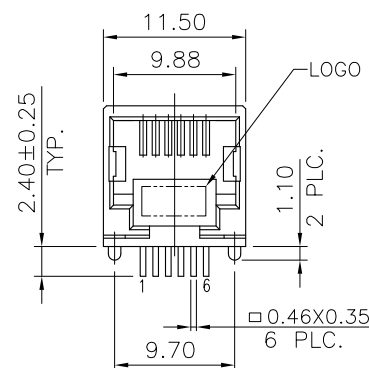
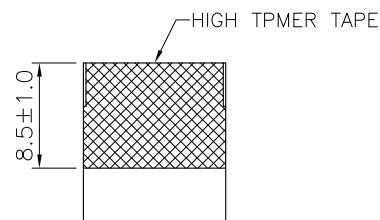
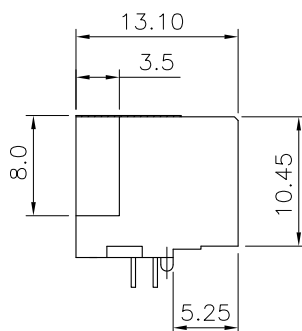
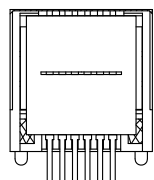
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LOC
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REVISIONS

P	LTR	DESCRIPTION	DATE	DWN	APVD
		SEE SHEET 1.			



RECOMMENDED PCB LAYOUT (THICKNESS: 1.6mm)
DIMENSION TOLERANCE: 1 PLC: ±0.1 2PLC: ±0.05

NOTE:

- MATERIAL:
HOUSING: PA46 WITH 30% GF, UL94 V-0, BLACK COLOR.
CONTACTS: PHOSPHOR BRONZE.
SHIELD: BRASS.
- FINISH:
CONTACTS: (SEE TABLE) GOLD PLATED ON CONTACT AREA, GOLD FLASH ON SOLDER TAIL, WITH ENTIRE CONTACT UNDERPLATED 1.27μm [50μ"] MIN. NICKEL.
- WAVE SOLDER CAPABLE TO 265°C PER 109-202, CONDITION B.

4. OBSOLETE PARTS: OBSOLETE CIS STREAMLINING PER D.RENAUD/D.SINISI

OBSOLETE	6P6C	REEL	1.27μm [50μ"]	1-1734723-8
			0.762μm [30μ"]	1-1734723-7
			0.381μm [15μ"]	1-1734723-6
			0.152μm [6μ"]	1-1734723-5
OBSOLETE	6P6C	TRAY	1.27μm [50μ"]	1-1734723-4
			0.762μm [30μ"]	1-1734723-3
			0.381μm [15μ"]	1-1734723-2
			0.152μm [6μ"]	1-1734723-1
	RJ11	PACKAGE	MIN. GOLD THICKNESS	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN A. WU 10MAR2008	 TE Connectivity	
DIMENSIONS: MM		CHK S. HOU 10MAR2008		
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD W. KODAMA 10MAR2008	NAME MODULAR JACK, RJ11, SINGLE, DIP TYPE	
MATERIAL SEE NOTE		FINISH SEE NOTE		
CUSTOMER DRAWING		PRODUCT SPEC 108-57527	SIZE A3	
WEIGHT 2.5 GRAMS		APPLICATION SPEC —	CAGE CODE —	
SCALE —		DRAWING NO C=1734723	RESTRICTED TO —	
SHEET 2 OF 5		REV A2		

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LOC

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REVISIONS

DW

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LTR

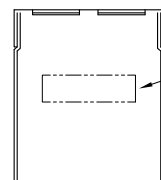
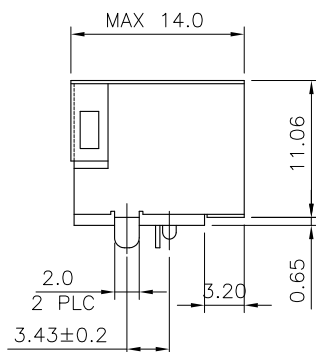
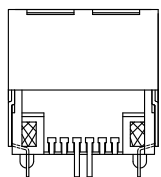
DESCRIPTION

DATE

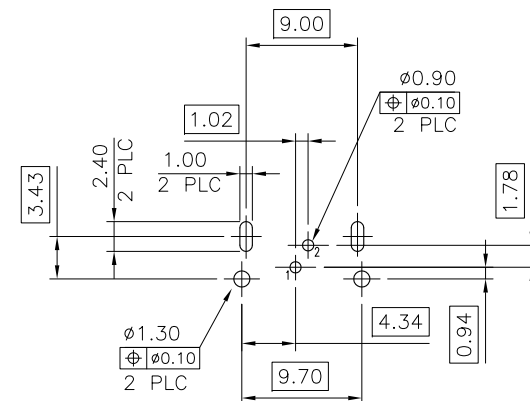
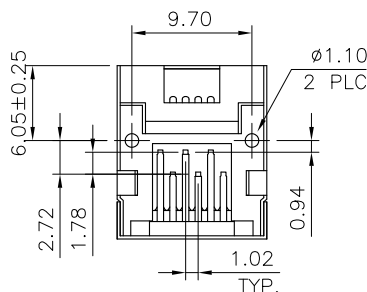
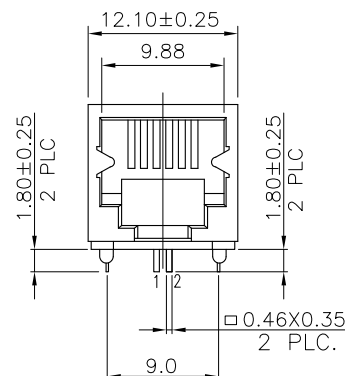
DWN

APVD

SEE SHEET 1.



LOGO



RECOMMENDED PCB LAYOUT (THICKNESS: 1.6mm)
DIMENSION TOLERANCE: 1 PLC: ±0.1 2PLC: ±0.05

NOTE:

- MATERIAL:
HOUSING: PA46 WITH 30% GF, UL94 V-0, BLACK COLOR.
CONTACTS: PHOSPHOR BRONZE.
SHIELD: BRASS.
- FINISH:
CONTACTS: (SEE TABLE) GOLD PLATED ON CONTACT AREA, GOLD FLASH ON SOLDER TAIL, WITH ENTIRE CONTACT UNDERPLATED 1.27μm [50μ"] MIN. NICKEL.
SHIELD: 0.51μm [20μ"] MIN. NICKEL PLATED.
- WAVE SOLDER CAPABLE TO 265°C PER TE TEST SPEC. 109-202, CONDITION B.

OBSOLETE	6P2C	REEL	1.27μm [50μ"]	4-1734723-8
			0.762μm [30μ"]	4-1734723-7
			0.381μm [15μ"]	4-1734723-6
			0.152μm [6μ"]	4-1734723-5
OBSOLETE		TRAY	1.27μm [50μ"]	4-1734723-4
			0.762μm [30μ"]	4-1734723-3
			0.381μm [15μ"]	4-1734723-2
			0.152μm [6μ"]	4-1734723-1
	RJ11	PACKAGE	MIN. GOLD THICKNESS	PART NUMBER

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DWN A. WU 10MAR2008

CHK S. HOU 10MAR2008

APVD W. KODAMA 10MAR2008

PRODUCT SPEC

108-57527

APPLICATION SPEC

—

WEIGHT 3 GRAMS

CUSTOMER DRAWING



TE Connectivity

NAME

MODULAR JACK, RJ11,
SINGLE, DIP TYPE

SIZE

CAGE CODE

DRAWING NO

RESTRICTED TO

A3

—

C=1734723

—

SCALE —

SHEET

3 OF 5

REV A2

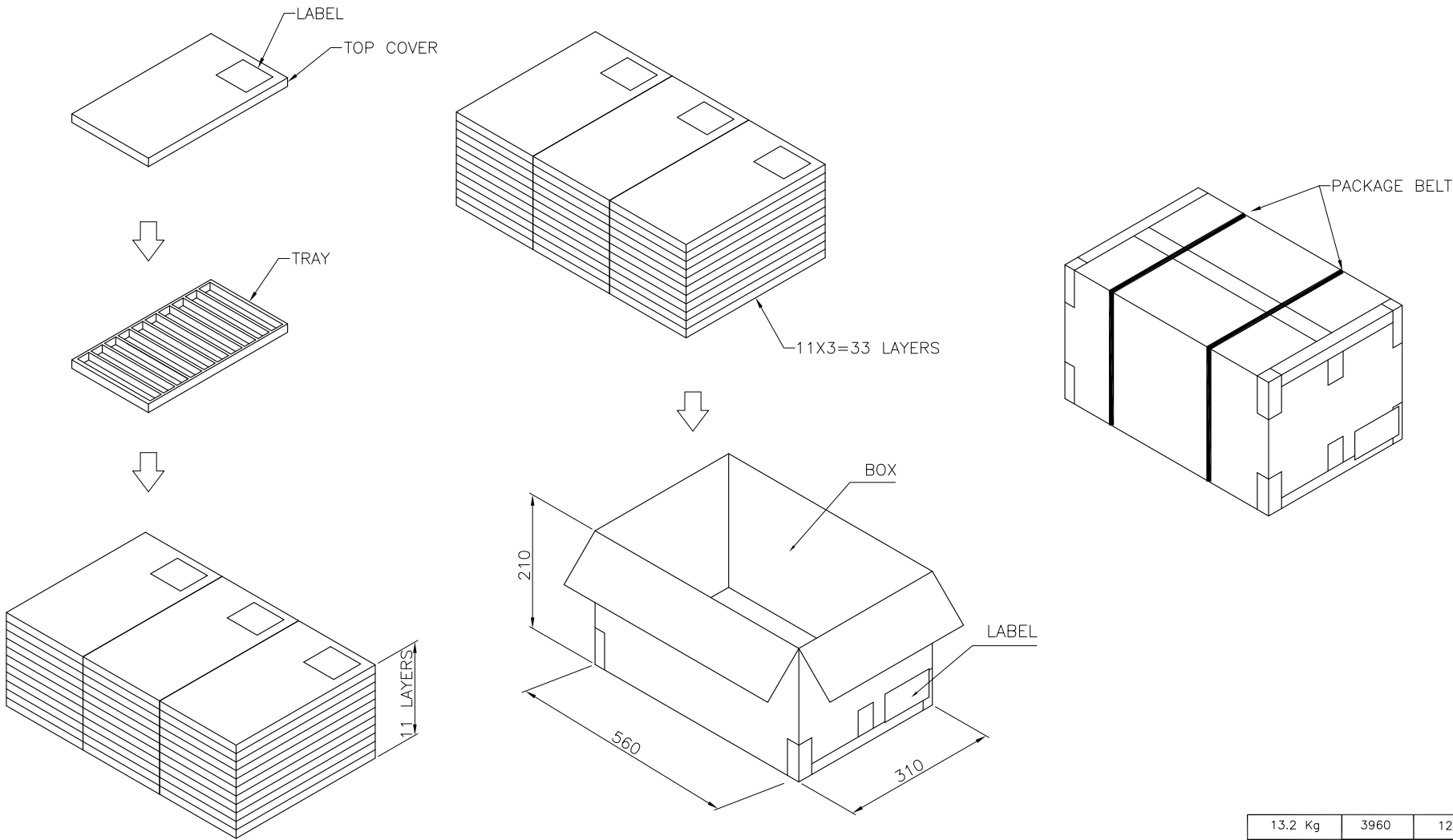
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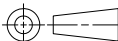
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1

LOC	DIST	REVISIONS					
DW	—	P	LTR	DESCRIPTION	DATE	DWN	APVD
				SEE SHEET 1.			



13.2 Kg	3960	120	1734723-1
GROSS WEIGHT	TOTAL	PCS/TRAY	PART NUMBER

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN A. WU	10MAR2008	 TE Connectivity			
		CHK S. HOU	10MAR2008				
		APVD W. KODAMA	10MAR2008				
DIMENSIONS: MM		TOLERANCES UNLESS OTHERWISE SPECIFIED:		NAME			
		0 PLC ± - 1 PLC ± - 2 PLC ± - 3 PLC ± - 4 PLC ± - ANGLES ± -		MODULAR JACK, RJ11, SINGLE, DIP TYPE			
MATERIAL		FINISH		SIZE	CAGE CODE	DRAWING NO	RESTRICTED TO
				A3	-	C=1734723	-
CUSTOMER DRAWING				SCALE		SHEET	REV
				-		4 of 5	A2

4

3

2

1

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LOC
DWDIST
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REVISIONS

P

LTR

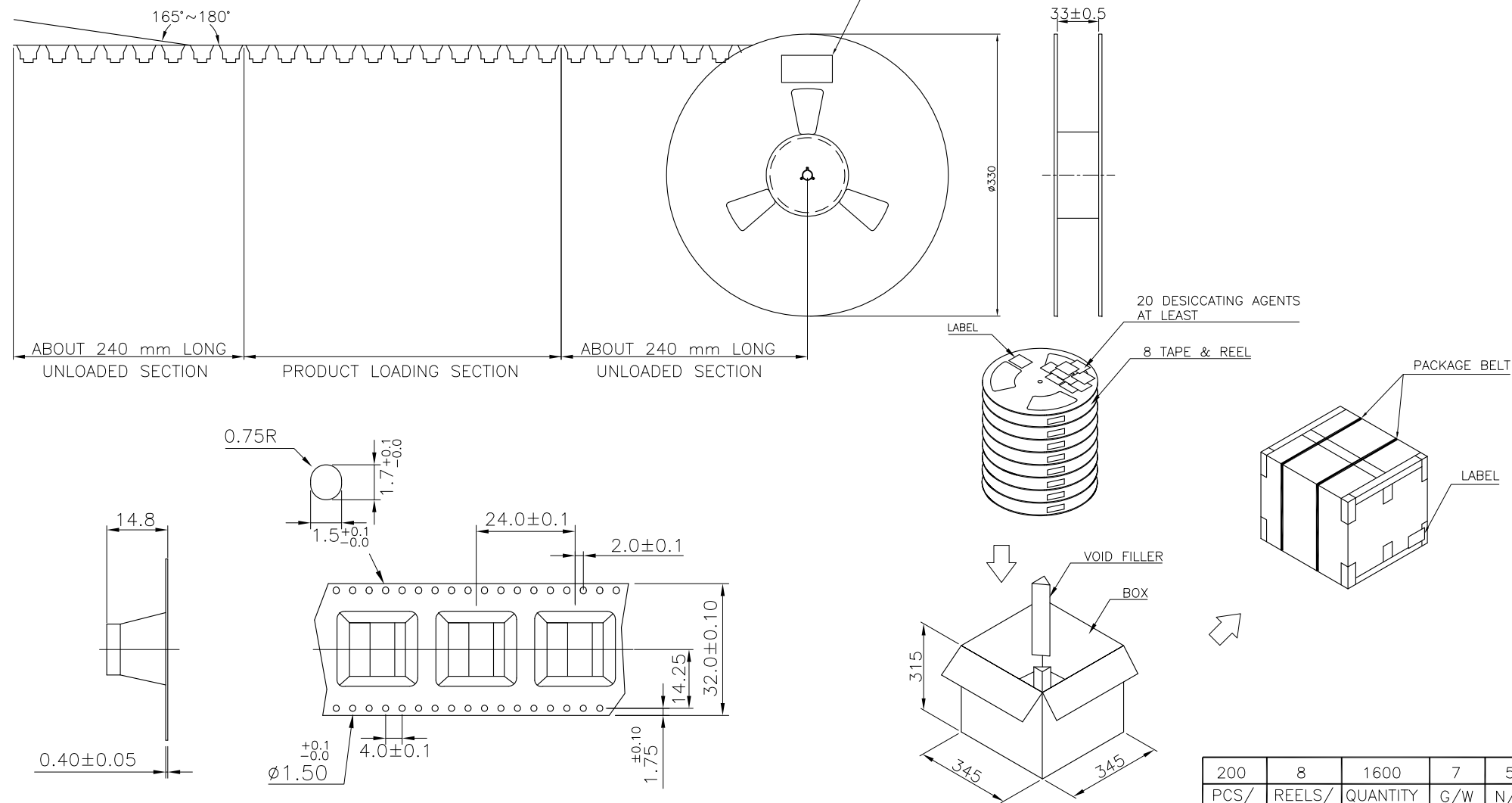
DESCRIPTION

DATE

DWN

APVD

SEE SHEET 1.



200	8	1600	7	5
PCS/ TAPE	REELS/ BOX	QUANTITY (PCS)	G/W (Kg)	N/W (Kg)

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DWN
A. WU
10MAR2008CHK
S. HOU
10MAR2008APVD
W. KODAMA
10MAR2008

PRODUCT SPEC

APPLICATION SPEC

WEIGHT

—

CUSTOMER DRAWING

STE TE ConnectivityMODULAR JACK, RJ11,
SINGLE, DIP TYPESIZE
A3CAGE CODE
—DRAWING NO
C=1734723RESTRICTED TO
—SCALE
—SHEET
5 of 5REV
A2

Данный компонент на территории Российской Федерации

Вы можете приобрести в компании MosChip.

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

Офис по работе с юридическими лицами:

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